

1.53(b) Continuation of Serial No.: 09/951,501  
 Attorney Docket No.: 1607.1001CIP/C

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FORM PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTORNEY DOCKET NO. 1607.1001 CIP/C	APPLICATION NO. 10/612,042
LIST OF REFERENCES CITED BY APPLICANT  (Use several sheets if necessary)		FIRST NAMED INVENTOR Prakash Khatri	
		FILING DATE July 3, 2003	GROUP ART UNIT 1764

**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL		DOCUMENT NO.	DATE	NAME	CLASS	SUB-CLASS	FILING DATE
GJU	AA	3,669,884	6/13/72	Wright	252	36	
GJU	AB	4,738,737	4/19/88	Runde et al.	156	91	
GJU	AC	4,803,100	2/7/89	Ameen et al.	427	387	
GJU	AD	5,167,851	12/1/92	Jamison et al.	252	74	
GJU	AE	5,194,480	3/16/93	Block et al.			
GJU	AF	5,250,209	10/5/93	Jamison et al.	252	74	
GJU	AG	5,298,791	3/29/94	Liberty et al.	257	707	
GJU	AH	5,904,796	5/18/99	Freuler et al.	156	278	
GJU	AI	6,049,458	4/11/00	Lee et al.	361	705	
GJU	AJ	6,054,198	4/25/00	Bunyan et al.	428	40.5	
GJU	AK	6,059,116	5/9/00	Hinshaw et al.	206	714	
GJU	AL	6,114,429	9/5/00	Yamada, et al.	524	432	
GJU	AM	6,143,076	11/7/00	Rasmussen, et al.	118	411	
GJU	AN	6,174,841	1/01	Yamada et al.	508	172	
GJU	AO	6,255,257	7/01	Yamada et al.	508	172	
GJU	AP	6,286,212	9/01	Easton	29	890.03	
GJU	AQ	6,475,962	11/02	Khatri	508	161	

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**FOREIGN PATENT DOCUMENTS**

		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUB-CLASS	TRANSLATION YES    NO
<i>Gill</i>	AR	WO/00/36893	6/22/00	WIPO	—	—	
<i>Gill</i>	AS	EP 0906945	4/7/99	EPC	—	—	

**OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)**

<i>Gill</i>	AT	Advanced Thermal Interface Material: 'Dry-To-The-Touch' Thermal Grease by Khatri and Ziemske, March, 2001.
<i>Gill</i>	AU	"Sprayable Thermal Grease Dramatically Reduces Labor While Offering Other Unique Advantages" by Khatri and Ziemske, 1999.
<i>Gill</i>	AV	Article entitled, "Thermal Isolators", <u>PCIM</u> , April 1999 (pp. 57-61)
<i>Gill</i>	AW	Chomerics Technical Bulletin 69, "CHO-TERM T500", 10/99 (2pgs)
<i>Gill</i>	AX	Power Devices, Inc. "Powerstrate" Advertisement (1 pg.), date unknown
<i>Gill</i>	AY	Article entitled, "Differential Phase Change Thermal Interface Materials", Technological Horizons (2 pgs.), date unkown
<i>Gill</i>	AZ	Article entitled "Thermal Gap Fillers," <u>PCIM</u> , September 1999 (pp. 24-25, 27)
<i>Gill</i>	BA	Article entitled "Navigating the Maze of Thermal Interface Materials," Electronic Product Supplement, ( <a href="http://www.electronicsproducts.com">http://www.electronicsproducts.com</a> ) Fall, 1999 (5 pp.)
<i>Gill</i>	BB	Article entitled "Thermal Resistance of Interface Materials as a Function of Pressure," Latham, (2 pp.), ( <a href="http://www.electronics-cooling.com/Resources/EC_Articles/SEP96/sep96_tb.htm">http://www.electronics-cooling.com/Resources/EC_Articles/SEP96/sep96_tb.htm</a> ).
<i>Gill</i>	BC	Wakefield Engineering advertisement "Thermal Compounds, Adhesives, Interface Materials, Hardware, Installation Tools (1 pg.), believed dated 1997 or before.
<i>Gill</i>	BD	Bergquist Company Brochure "Sil-Pad Design Guide" 1997-1998 (1 pg.)
<i>Gill</i>	BE	Chomerics Company (Division of Parker-Hannifin) Advertisement, (1 pg.), from Electronics Cooling, Vol. 7, No. 1, February 2001
<i>Gill</i>	BF	Fujipoly Company advertisement from <u>PCIM</u> , January 2000, page 14
<i>Gill</i>	BG	MHW brochure regarding Keratherm® (2 pp.), February 1999
<i>Gill</i>	BH	MHW International Corp. advertisement from <u>Electronics Cooling</u> , Vol. 7, No. 1, February 2001, page 13
<i>Gill</i>	BI	W.L. Gore & Assoc. advertisement (1 pg.) from <u>Electronic Packaging and Production</u> , June 2001
<i>Gill</i>	BJ	Emerson & Cuming (division of National Starch and Chemical Company), advertisement (1 pg.)
<i>Gill</i>	BK	Honeywell advertisement (1 pg.) from <u>Electronics Cooling</u> , Vol. 7, No. 1, February 2001

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<i>Glu</i>	BL	"Electrolube's Unique Heat Transfer Compound Aerosol Optimises Board Thermal Performance," July 28, 2000 website pages (5 pp.)
<i>Glu</i>	BM	AOS brochure describing thermal greases.
<i>Glu</i>	BN	Article entitled "Attaching Heat Sinks to Components," Electronic Packaging & Production, pp. 42-46, July 1997
<i>Glu</i>	BO	Article entitled "Thermal Interface Materials," deSorgo et al., found at <a href="http://www.cooling-electronics.com/Resources/EC_Articles/SEP96/sep96_01.htm">http://www.cooling-electronics.com/Resources/EC_Articles/SEP96/sep96_01.htm</a> (6 pp.)
<i>Glu</i>	BP	Article entitled "Thermal Management Materials and Designs," <u>Electronic Packaging and Production</u> , October 2000 (pgs. 50-57).
<i>Glu</i>	BQ	Thermalloy Company Press Release (1 pg.), December 18, 1996.
<i>Glu</i>	BR	Article entitled "Cooling Technologies - Work With Microprocessors Points the Way to Thermal Management Improvements for Power Semiconductors," <u>PCIM</u> , May 1999 (6 pp.)
<i>Glu</i>	BS	Article entitled "Test Methods for Characterizing the Thermal Transmission Properties of Phase-change Thermal Interface Materials," ( <a href="http://www.electronics-cooling.com/html1/1999_may/article1.html">http://www.electronics-cooling.com/html1/1999_may/article1.html</a> ), May 1999 (9 pp.)
<i>Glu</i>	BT	Brochure for Thermagon Company (5 pp), ©1997.
<i>Glu</i>	BU	Brochure for Orcus, Inc., (3 pp.), ©1998.
<i>Glu</i>	BV	Brochure for Bergquist Company (5 pp.), ©1998.
<i>Glu</i>	BW	Advertisement for Bergquist Company "Thermal Performance you must see to believe," (1 pg.), undated
<i>Glu</i>	BX	Brochure for Power Devices Company (11 pp.), ©1996
<i>Glu</i>	BY	Brochure for Chomerics Company (6 pp.), October 1999
<i>Glu</i>	BZ	Advertisement for Chomerics Company's "Therm-A-Gap" Gap Filling Materials, (1 pg.), October 1999
<i>Glu</i>	CA	Advertisement for "GAP PAD VO," (1 pg.), undated
<i>Glu</i>	CB	Advertisement for Fujipoly Company's "SARCON Thermal Management Components," (1 pg.), undated.
<i>Glu</i>	CC	Advertisement for Fujipoly Company's "SARCON Heat Sink Gel Pads," (1 pg.), undated
<i>Glu</i>	CD	Abstract regarding WO 0036893, entitled, "Method of Applying a Phase-Change Thermal Interface Material" published June 22, 2000 (1 pg.)

NAME: *Eileen DeLoach*

DATE *20 July 2004*